

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32MP133AAG3	244M*501XXXY	A	9991	28-10-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	500.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	NAC	Copper Alloy	SACN305	

Package Designator	Size	Nbr of instances	Shape	
BGA	9x9	289	bulk solder	
Comment	Package : B0EB TFBGA 9X9 289L PITCH 0.5 MM DM00699787			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	244M*501XXY				6000002.0	1000000.0								
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)								
Die or dies	M-011 Other inorganic materials	7.220	mg	supplier	die	Silicon (Si)	7440-21-3		6.700	mg	927978	13400								
				supplier	metallization	Aluminium (Al)	7429-90-5		0.058	mg	8033	116								
				supplier	metallization	Copper (Cu)	7440-50-8		0.171	mg	23684	342								
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	139	2								
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.029	mg	4017	58								
				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	970	14								
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	139	2								
				supplier	Passivation	Silicon Nitride	12033-89-5		0.041	mg	5679	82								
				supplier	Passivation	Silicon Oxide	7631-86-9		0.212	mg	29363	424								
				Substrate (A29368)	M-011 Other inorganic materials	180.145	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Proprietary		24.590	mg	136500	49180				
supplier	BT-substrate	Glass cloth	65997-17-3						56.926	mg	316000	113852								
supplier	BT-substrate	Copper foil	7440-50-8						75.120	mg	417000	150241								
supplier	Solder mask	2-benzyl-2-dimethylamino-4-morpholinobutyr	119313-12-1						8.197	mg	45500	16393								
supplier	Solder mask	Naphtha (petroleum), heavy aromatic	64742-94-5						8.107	mg	45000	16213								
supplier	Solder mask	TALC (CONTAINING NO ASBESTOS FIBRES)	14807-96-6						6.035	mg	33500	12070								
supplier	Solder mask	1,3,5-Triazine-2,4,6-triamine	108-78-1						1.171	mg	6500	2342								
supplier	film	Copper (Cu)	7440-50-8						3.059	mg	786250	6117								
supplier	film	Silver (Ag)	7440-22-4						0.204	mg	52500	408								
supplier	film	2,2-dimethyl-1,3-propanediyl bismethacrylate	1985-51-9						0.165	mg	42500	331								
DAF (2100AC)	M-011 Other inorganic materials	3.890	mg	supplier	film	A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl)g	Proprietary		0.219	mg	56205	437								
				supplier	film	2-[[[2,2-bis[[[1-oxoallyloxy)methyl]butoxy]met	94108-97-1		0.152	mg	39195	305								
				supplier	film	tert-butyl peroxyneodecanoate	26748-41-4		0.088	mg	22500	175								
				supplier	film	Hydroquinone	123-31-9		0.003	mg	850	7								
				Bonding wire (Cu)	Precious metals	4.606	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		4.447	mg	965500	8894				
								supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.143	mg	31000	286				
								supplier	Bonding wire	Gold (Au)	7440-57-5		0.016	mg	3500	32				
								Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	280.420	mg	supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		252.378	mg	900000	504756
												supplier	Molding Compound	Epoxy resin	Proprietary		11.217	mg	40000	22434
				supplier	Molding Compound	Phenol resin	Proprietary		15.704	mg	56000	31407								
supplier	Molding Compound	Carbon Black	1333-86-4		1.122	mg	4000	2243												
Solder balls (SACN305)	M-011 Other inorganic materials	23.719	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		22.877	mg	964500	45754								
				supplier	Matte Sn	Silver(Ag)	7440-22-4		0.712	mg	30000	1423								
				supplier	Matte Sn	Copper (Cu)	7440-50-8		0.119	mg	5000	237								
				supplier	Matte Sn	Nickel (Ni)	7440-02-0		0.012	mg	500	24								